



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Board Level Cooling – Bond On 2292



BOARD LEVEL COOLING – Bond On 2292

Bond On 2292 is a circular board level heat sink designed to cool Leadless Chip Carriers, Flat Packs, and 68 position devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
2292BG	Leadless Chip Carriers, Flat Packs and 68 position



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Black Anodize
Device Attachment Options	Epoxy
Thermal Interface Material	Epoxy

Property	Details
Heat Sink Width (mm)	28.58
Heat Sink Length (mm)	28.58
Heat Sink Height (mm)	9.14
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

